DESIGN SPECIFICATIONS FOR PCB MANUFACTURING

Document No.RD24-65	MTI-200-1-230111

RESEARCH AND DEVELOPMENT DEPARTMENT
MICROTECH INDUSTRIES PVT. LTD. PAKISTAN

Contents

Design Distribution Policy

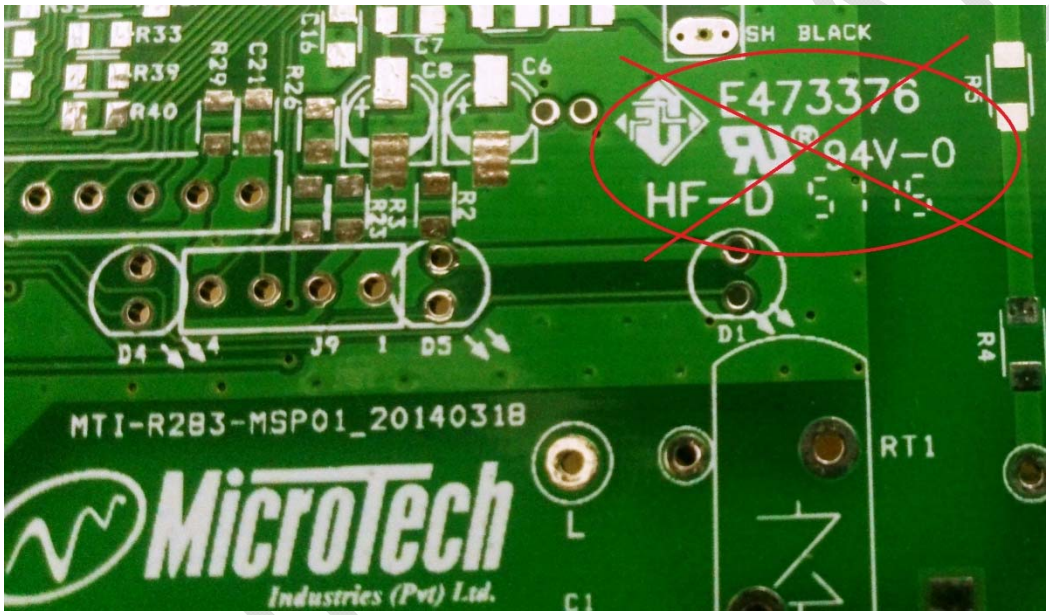
The Design of the PCB is a highly confidential asset that should NOT be shared with any other organization or manufacturer without written consent. The design should NOT be shared with the other departments of Micro tech Industries under any circumstances. This includes price negotiations and conflict resolving email. The technical Problem regarding PCB manufacturing or any issue that needs further elaboration/discussion should be communicated to the R&D person that sent you the Gerber files. The issues regarding payments/shipping should be communicated to procurement department.

Introduction

This document serves as a basic mean for conveying the requirements that are required for PCB manufacturing. The object of the document is to convey the technical requirements to the manufacturer along with other requirements. The detail of these requirements is given below.

Manufacturer and Certifications LOGO

Do not print the LOGOs for manufacturer or any other certification markings i.e. UL rating RU specifications or any other number etc. on PCB.

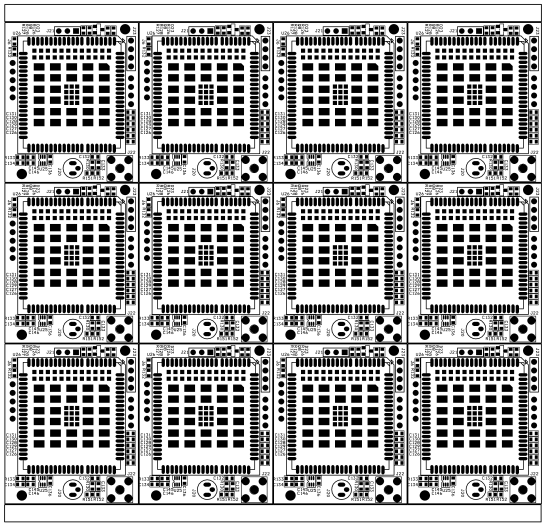


PCB Design Information

The design information regarding PCB material, dimensions, number of layer , color of solder mask, thickness of FR4 material etc. are given in the table below:

PCB design information	
PCB name	**MTI-200-1-230111**
PCB size (single module)	**1.55 x 1.856 inch (2.8768sqinch)**
PCB panel size with extended PCB	**NIL**
Layers	**2**
Number of PCBs in ONE panel	**12**
Required PCB quantity	
Board Thickness	1.6mmGreen
Copper Foil Thickness	35um
Material	FR-4 KB6160, 1oz, Cu, (Finish)
Finishing	Lead free HASL
Solder mask	**Green**
Solder Mask Type	KGS-6188G
V-CUT	**Yes**
V-CUT Thickness	
Electrical Test / E. test	Yes/Mark at board edge
BOW and Twist	≤0.75%
Thermal Stress Test	288°C/10 Sec
Via hole	
P.T.H. Thickness	20um
Silk Screen Layer	White
Date code week/year Print on silk screen layer	
Component Marking Type	M-211(W)
Tin/Lead Thickness	≥1um
Top and Bottom Registration	+/- 3Mills
Solder test	≥95% with plum tin plating
Hardness test	6 H

Screen Shot of the PCB



Cutting slot information